

Click here for the 3D model.

| Dimensions |  |
| :--- | :--- |
| Chip Size | 0805 |
| L | $2 \mathrm{~mm}+/-0.2 \mathrm{~mm}$ |
| W | $1.25 \mathrm{~mm}+/-0.2 \mathrm{~mm}$ |
| T | $1.25 \mathrm{~mm}+/-0.15 \mathrm{~mm}$ |
| S | 0.75 mm MIN |
| B | $0.5 \mathrm{~mm}+/-0.25 \mathrm{~mm}$ |

Packaging Specifications

| Packaging | T\&R, 180mm, Plastic Tape |
| :--- | :--- |
| Packaging Quantity | 2500 |

SMD Comm X7R FO, Ceramic, 0.068 uF, 20\%, 100 VDC, X7R, SMD, MLCC, Open Mode, Temperature Stable, 0805

| General Information |  |
| :--- | :--- |
| Series | SMD Comm X7R FO |
| Style | SMD Chip |
| Description | SMD, MLCC, Open Mode, Temperature Stable |
| Features | Open Mode, Temperature Stable |
| RoHS | Yes |
| Termination | Tin |
| Marking | No |
| AEC-Q2OO | No |
| Component Weight | 21 mg |
| Shelf Life | 78 Weeks |
| MSL | 1 |


| Specifications | 0.068 uF |
| :--- | :--- |
| Capacitance | 1 kHz 1.0 Vrms |
| Measurement Condition | $20 \%$ |
| Capacitance Tolerance | 100 VDC |
| Voltage DC | 250 VDC |
| Dielectric Withstanding Voltage | $-55 /+125^{\circ} \mathrm{C}$ |
| Temperature Range | X 7 R |
| Temperature Coefficient | $15 \%, 1 \mathrm{kHz} 1.0 \mathrm{Vrms}$ |
| Capacitance Change with Reference |  |
| to +25 ${ }^{\circ} \mathrm{C}$ and O VDC Applied (TCC) | $2.5 \% 1 \mathrm{kHz} 1.0 \mathrm{Vrms}$ |
| Dissipation Factor | $3 \%$ Loss/Decade Hour: |
| Aging Rate | 14.7059 GOhms |
| Insulation Resistance |  |

